FEATURES
1. GENERAL CHARACTERISTICS
   DIMENSIONS: 12.20x9.54x1.35 mm
   WEIGHT: APPROX. 0.53g
   CONTACT PRINCIPLE: FRICTION TECHNOLOGY
   MOUNTING SYSTEM: SMT TYPE
   DURABILITY: 1,500 CYCLES MIN.

2. MECHANICAL CHARACTERISTICS
   INSULATION MATERIAL: LCP+30% G/F. UL 94V-0
   CONTACT MATERIAL: PHOSPHOR BRONZE
   SHELL MATERIAL: STAINLESS STEEL (SUS301-H)
   CONTACT PLATING: 3uM GOLD OVER NICKEL ON CONTACT POINT, GOLD
   SHELL PLATING: NICKEL OVERALL.
   FLASH ON SOLDER TAIL.

3. ELECTRICAL CHARACTERISTICS
   CURRENT RATING: 0.5A MAX.
   VOLTAGE RATING: 38V MAX.
   CONTACT RESISTANCE: 100m@120V MAX.
   ISOLATION RESISTANCE: >1000M OHMS
   DIELECTRIC STANDING VOLTAGE: 1000V AC RMS, 1 MINUTE
   OPERATING TEMPERATURE: -40°C TO 85°C

NOTES:
1. ACCEPTABLE SIM CARD SIZE SHOULD MEET GSM 11.11
   SPECIFICATION REQUIREMENT.

HOW TO ORDER

CH03-KB060 - HXR

CONTACT PLATING
H = 3uM GOLD ON CONTACT/GOLD
FLASH ON TAIL

LOCATING PEGS OPTIONS:
A = WITH PEGS (STANDARD)
B = WITHOUT PEGS

PACKAGING TYPE:
R = TAPE & REEL (1500PCS/REEL)

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Type: CH03-KB
Drawing Number:
Sheet 1 of 1

Revision 1.4
Unit: mm

Graded Conn. design and all specifications are subject to change without notice or obligation.
NOTES:
1. REEL DIAM: 33CM.
2. 1500PCS PER REEL.
3. 10 REELS PER FULL CARTON.